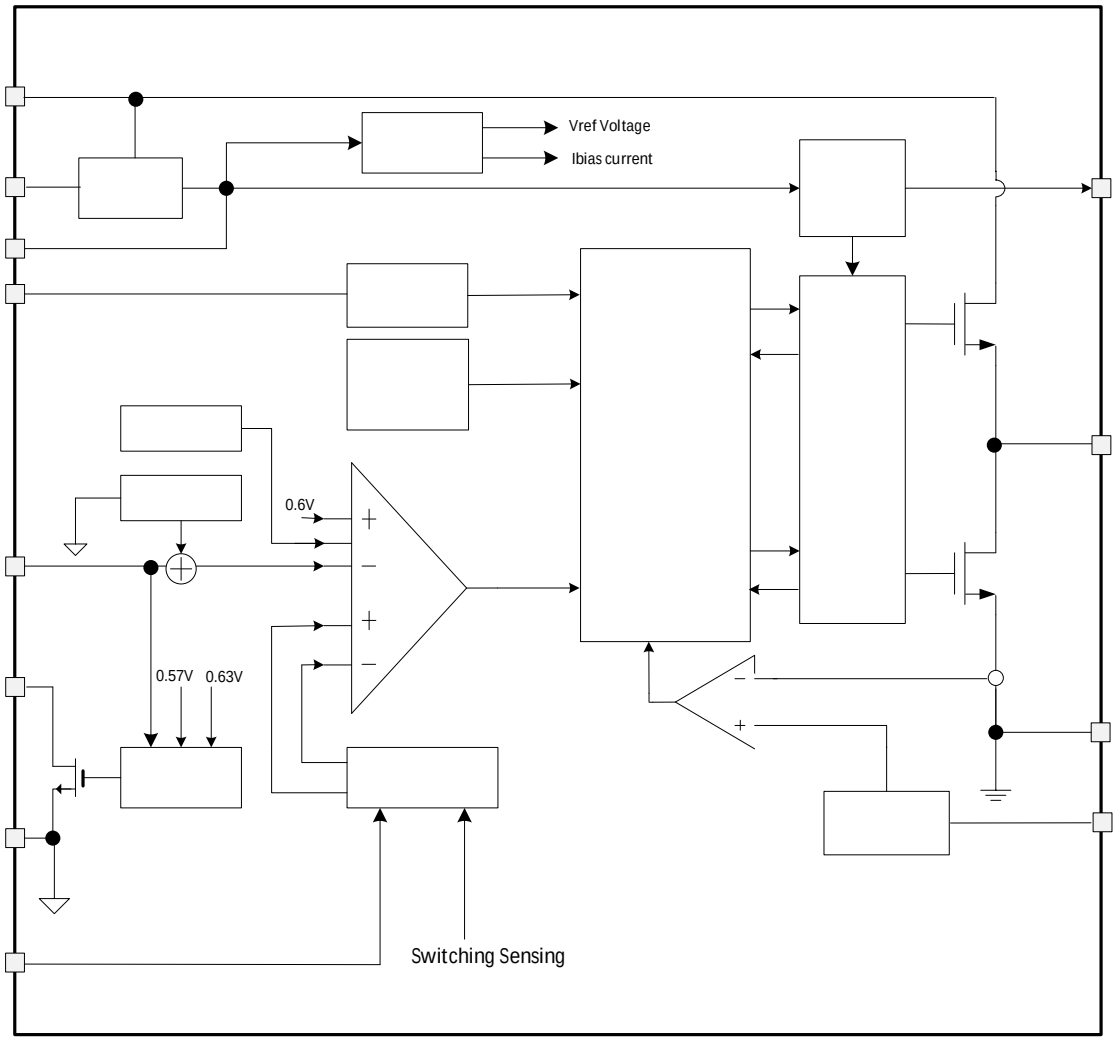
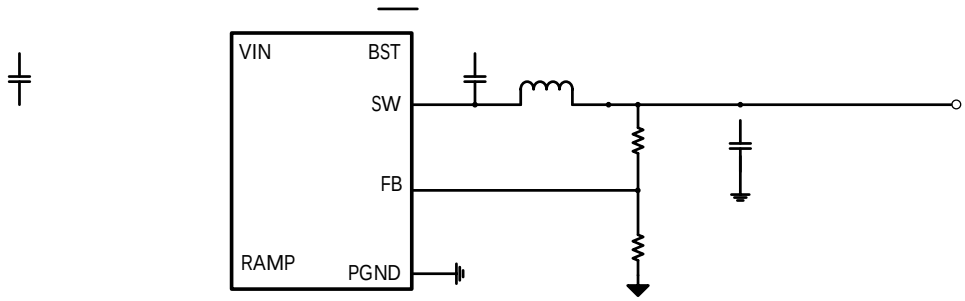
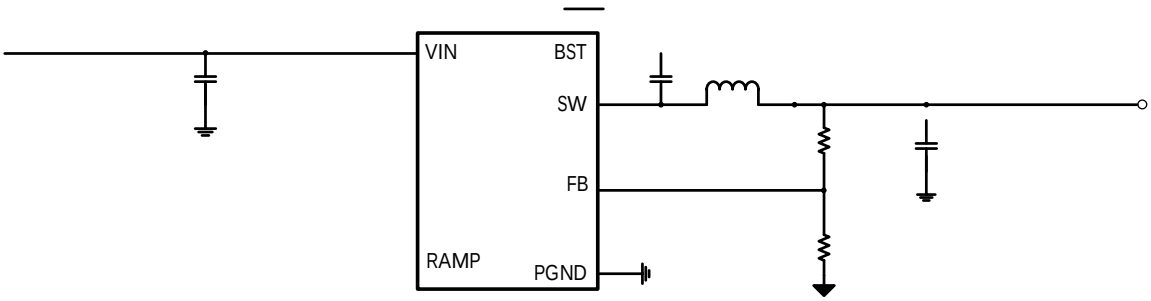
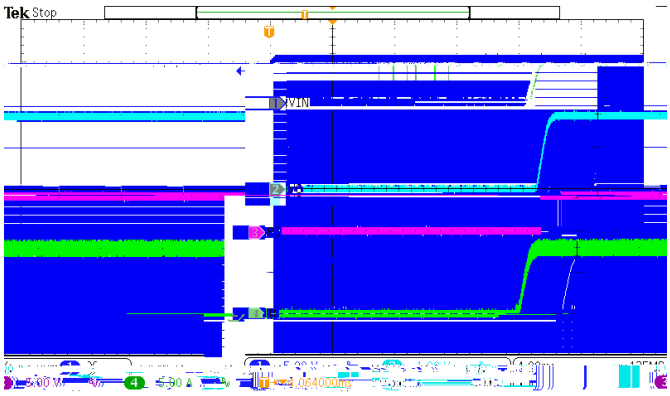
D I O R ...G..."†4 3$v À

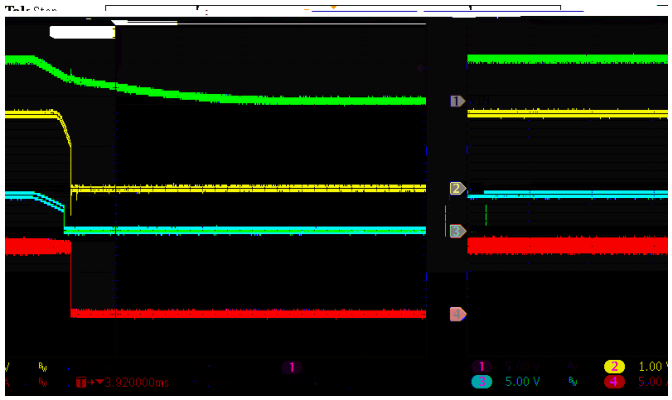
V L G H XY $ ƒ'8ep47

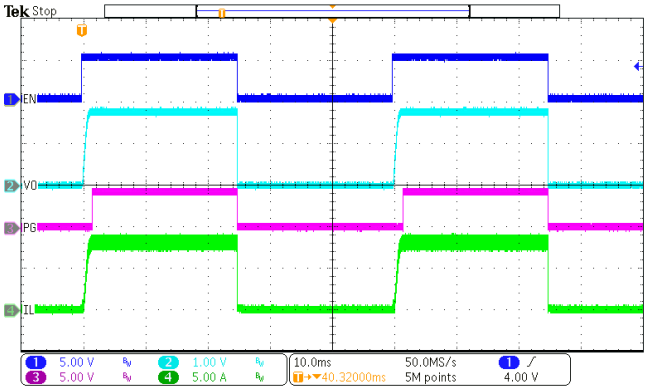

Vref Voltage
Ibias current
0.6V
0.57V
0.63V
Switching Sensing

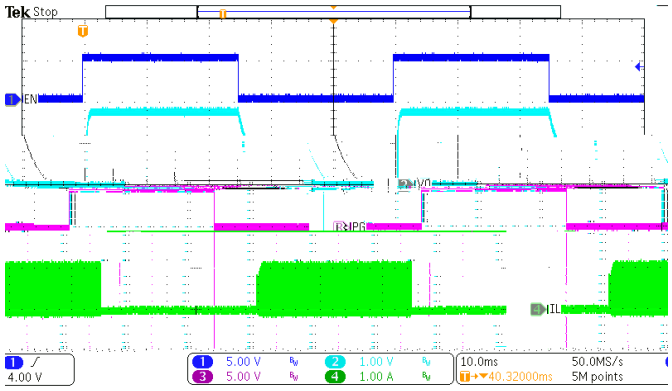

VIN
BST
SW
FB
RAMP
PGND


VIN
BST
SW
FB
RAMP
PGND

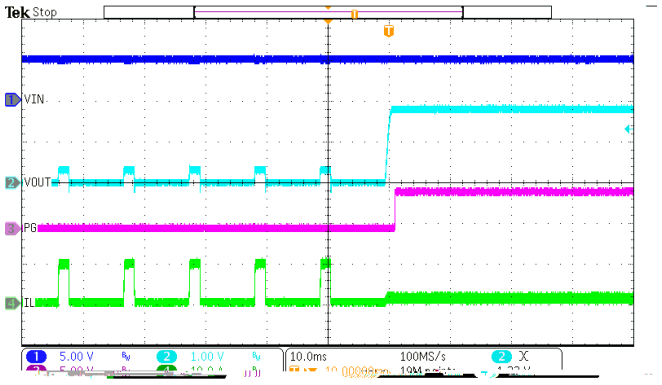

Tek Stop
VIN

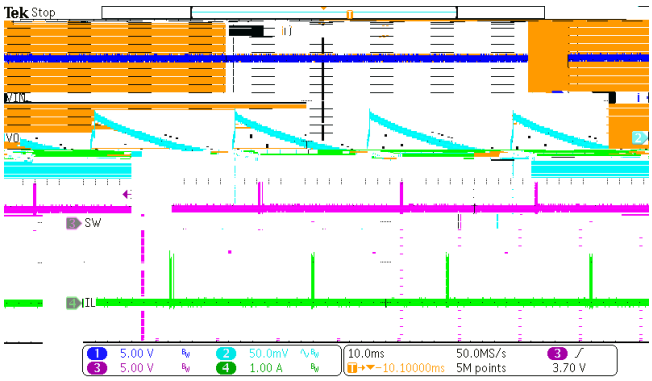

5.00 V

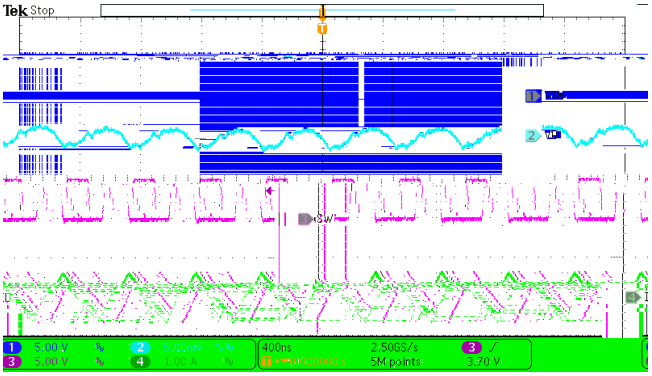

Tek Stop
EN
VO
PG
IL
5.00 V
1.00 V
5.00 V
5.00 A
10.0ms
50.0MS/s
40.32000ms
5M points
4.00 V

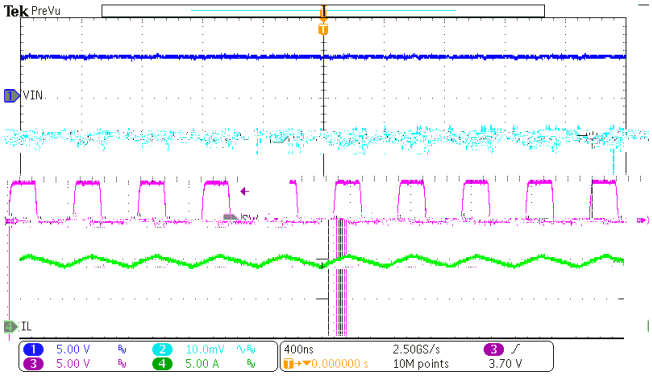

Tek Stop
EN
VO
PG
IL
4.00 V
5.00 V
1.00 V
5.00 V
1.00 A
10.0ms
40.32000ms
50.0MS/s
5M points

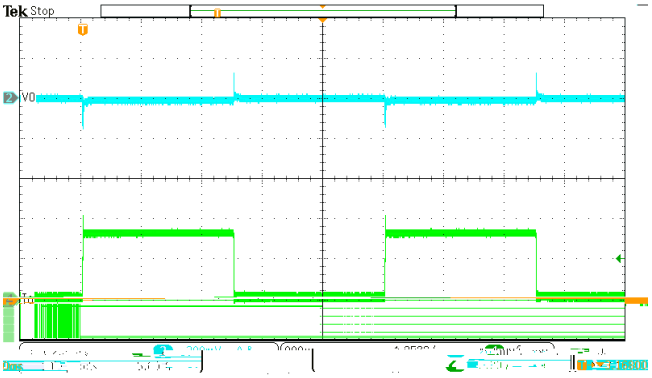


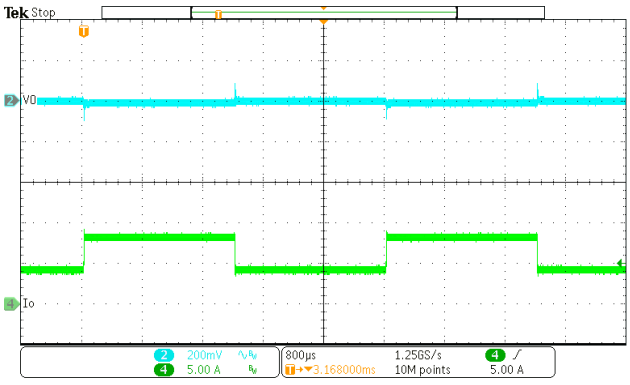

Tek Stop
VIN
VOUT
PG
IL
5.00 V
1.00 V
10.0ms
100MS/s

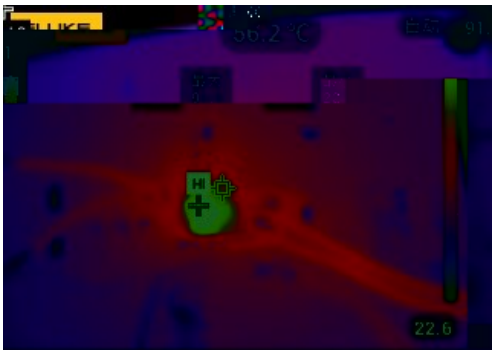

Tek Stop
VIN
VO
SW
IL
5.00 V
50.0mV
5.00 V
1.00 A
10.0ms
50.0MS/s
-10.10000ms
5M points
3.70 V


Tek Stop
VO
SW
400ns
2.50GS/s
5M points
3.70 V

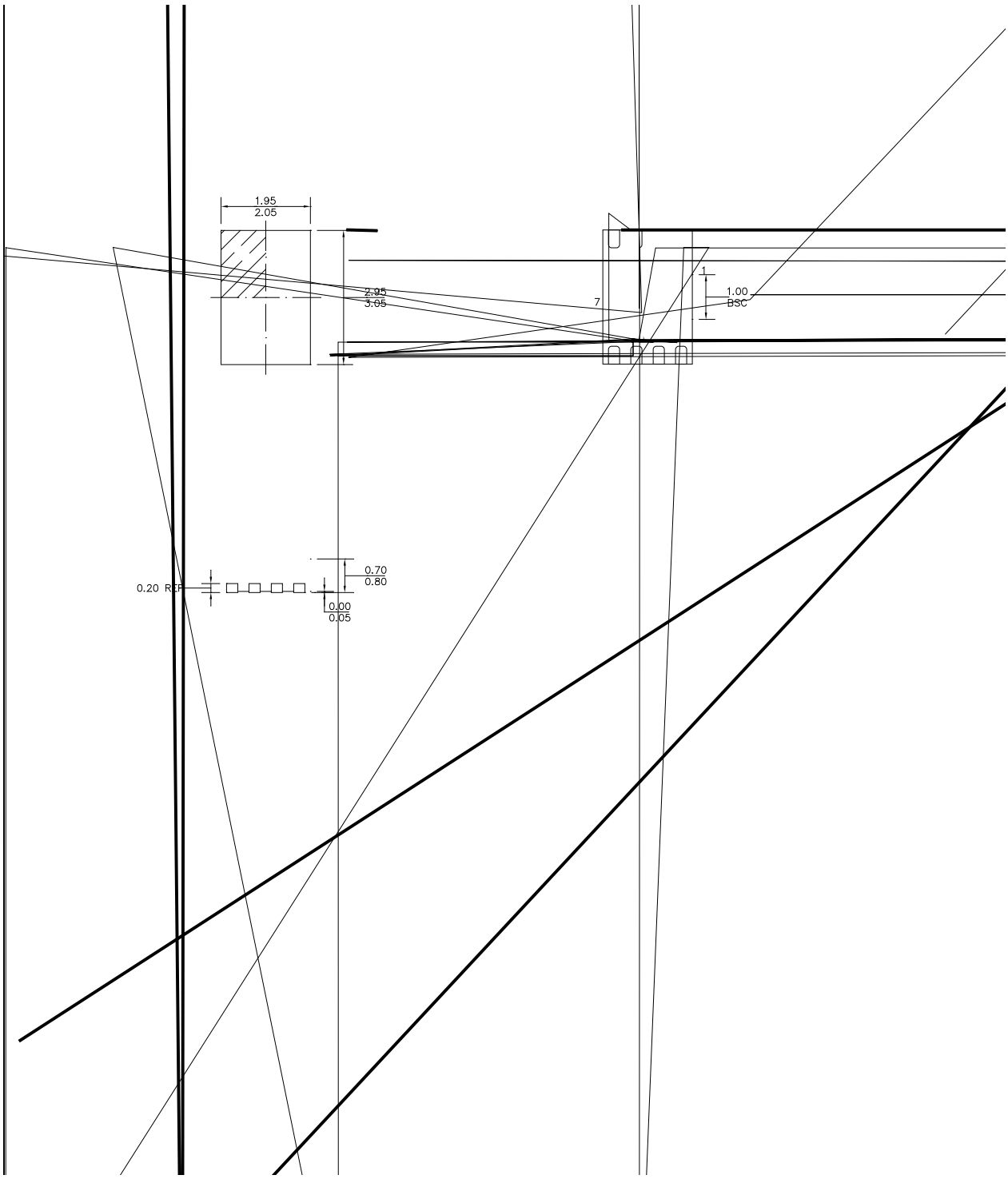

Tek PreVu
VIN
SW
IL
5.00 V
10.0mV
5.00 V
5.00 A
400ns
2.50GS/s
0.000000 s
10M points
3.70 V


Tek Stop
VO


Tek Stop
VO
Io
200mV
5.00 A
800µs
1.25GS/s
3.168000ms
10M points
5.00 A


22.6

The bottom layer is a large ground plane connected to the ground plane on top layer by vias it is recommended 8mil diameter drill holes of thermal vias, but a smaller via offers less risk of solder volume loss. On applications where solder volume loss through the vias is of concern, plugging or tenting can be used to achieve a repeatable process.


1.95
2.05
2.95
3.05
7
1
1.00
BSC
0.20 REF
0.70
0.80
0.00
0.05

